Application of the XT3D Multi-Point Flux Approximation to Vertically Staggered Grids or maybe Application of the XT3D Multi-Point Flux Approximation and Enhanced Grid Connectivity to Improve Accuracy of Flows in MODFLOW 6 Models With Steeply Sloping Layers Xt3d Enthusiast1 Some Company Xt3d Enthusiast2 Another Company August 19, 2022 11 Conflict of interest: None. 12 **Key words:** Key words ... 13 Article impact statement: Article impact statement ... 14 Abstract 15 This is the best paper ever...

#### $_{17}$ 1 Introduction

Some intro stuff here about MODFLOW (Hughes et al., 2017; Langevin et al., 2017, 2022) and XT3D

19 (Provost et al., 2017)...

### 20 Theoretical Background

- 21 Introduce vertically offset grids and explain the connection angle/length issue.
- Summarize XT3D and how it accounts for connection angle/length. Reference Kerry and Jim's demon-
- 23 stration that, in spite of that, XT3D doesn't really improve things for a steeply sloping grid. Must be
- 24 something else going on.
- 25 Explain wormholes and how they induce horizontal flow in a sloping channel regardless of XT3D.
- Grid with "connector cells"
- Role of flows between layers
- Shutting off flows between layers using extreme anisotropy in connector cells
- Sloping flow in connector cells
- Horizontal flow in flat-top cells
- Squashing of connector cells VO grid with horizontal flows and "wormholes"
- Proposed solution is to introduce cross-connections between layers.

## 3 Approach

- 34 Summarize the overall approach here.
- Will use a DISV plan-view model with connector cells and XT3D to demonstrate the "wormhole" effect
- discussed in the Theoretical Background in the limit as connector cells are squashed out. (Also can look
- at the other limit, as flat-top cells are squashed and connector cells dominate, so grid follows the channel
- 38 boundary.)
- Will use a DIS cross-sectional model to show results you get on a vertically staggered grid (without
- 40 cross-connections), with and without XT3D. (Basically what Kerry and Jim showed.)
- Will convert the DIS grid to a DISU grid with cross-connections and show improved results, with and
- without XT3D.

# 4 Description of Test Problems

Describe the test problem setups here.

- 4.1 Test problem 1 (DISV plan-view with connector cells)
- 46 Test problem 1...
- 4.2 Test problem 2 (DIS cross-sectional)
- Test problem 2...
- 4.3 Test problem 3 (DISU cross-sectional with cross-connections)
- Test problem 3...

#### 5 Results and Discussion

### 52 6 Conclusions

## 53 7 Acknowledgments

Thank all those reviewers.

## 55 8 Software Availability

- 56 MODFLOW 6 is open source; software is developed following modern software development principles. FloPy
- 57 (Bakker et al., 2016) contains full support for all MODFLOW 6 models and packages. We welcome input to
- the community through our public software repository. MODFLOW 6 is developed in the open, designed to
- 59 be teachable, runs on multilple

## 9 Supporting Information

# 10 Appendix

### 62 References

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